



Material Content Data Sheet



Sales Product Name	TLE7714G			Issued	28. August 2013			
MA#	MA001051278							
Package	PG-DSO-52-4			Weight*	869.11 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	17.200	1.98	1.98	19791	19791
leadframe	inorganic material	phosphorus	7723-14-0	0.073	0.01		84	
	non noble metal	zinc	7440-66-6	0.293	0.03		337	
	non noble metal	iron	7439-89-6	5.854	0.67		6736	
wire	non noble metal	copper	7440-50-8	237.701	27.35	28.06	273500	280657
	noble metal	gold	7440-57-5	2.311	0.27	0.27	2659	2659
	encapsulation	organic material	carbon black	1333-86-4	1.183	0.14		1361
encapsulation	plastics	epoxy resin	-	54.413	6.26		62608	
	inorganic material	silicondioxide	60676-86-0	535.848	61.65	68.05	616547	680516
leadfinish	non noble metal	tin	7440-31-5	7.508	0.86	0.86	8639	8639
plating	noble metal	silver	7440-22-4	0.968	0.11	0.11	1113	1113
glue	plastics	epoxy resin	-	1.440	0.17		1656	
	noble metal	silver	7440-22-4	4.319	0.50	0.67	4969	6625
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

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